1	20324	flip NEAR chip	USPAT;	2004/06
			•	2004/02
			US-PGPUB;	i
			EPO; JPO; DERWENT;	
			IBM_TDB	
2	20325	flip NEAR chip\$1	USPAT;	2004/02
-	20323	Inp 1122 11 0 11pu 1	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
3	120	(flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow	USPAT;	2004/02
	l	open\$3 hole\$1))	US-PGPUB; EPO; JPO;	
			DERWENT;	
	l		IBM_TDB	
4	19	(flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow	USPĀT;	2004/02
		open\$3 hole\$1) WITH bump\$1)	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
	20	(#2649002#   #2922622#   #2071610#   #4299941#   #4229642#	IBM_TDB USPAT	2004/02
5	28	("3648002"   "3832632"   "3971610"   "4288841"   "4329642"   "4340860"   "4437718"   "4554505"   "4739257"   "4899107"	USIAI	2004/02
		"4956605"   "5006792"   "5006796"   "5014161"   "5061192"		
		"5123850"   "5173451"   "5207585"   "5248262"   "5302891"		
		"5329423"   "5358417"   "5453701"   "5475315"   "5489854"		:
		"5493237"   "5633596"   "5656945").PN.	7.7.0.7. A 7.7.	0004/06
6	93	((flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow	USPAT; US-PGPUB;	2004/02
		open\$3 hole\$1))) and bump\$1	EPO; JPO;	
			DERWENT;	İ
			IBM_TDB	
7	74	(((flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow	USPAT;	2004/02
		open\$3 hole\$1))) and bump\$1) and (bond\$3 NEAR pad\$1)	US-PGPUB;	ļ
			EPO; JPO; DERWENT;	
			IBM TDB	
8	53	(flip NEAR chip\$1) and ((lead NEAR frame) WITH (tie NEAR bar\$1))	USPAT;	2004/02
	33	(Imp 1422 the empty) and (lease 1422 the mane) ****** (we 1422 the empty)	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
	_	(HEOOGO (AHILING) AGOOAH LUGOOOOOH LUGOOOOOH LUGOOGG (AHIL	IBM_TDB	2004/05
9	7	("5091341"   "5147821"   "5200809"   "5202288"   "5387554"	USPAT	2004/02
10	6	"5442234"   "5570272").PN. ("3729573"   "4377548"   "4470786"   "4626185"   "4823234"	USPAT	2004/02
.	١	"4954307").PN.		
11	34	((die NEAR pad\$4) WITH (concavit\$3 hollow open\$3 hole\$1) WITH	USPAT;	2004/02
		bump\$1)	US-PGPUB;	
			EPO; JPO; DERWENT;	
		•	IBM TDB	
12	994	(die NEAR pad\$4) WITH (concavit\$3 hollow open\$3 hole\$1)	USPAT;	2004/02
		(	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
12	70	((dia NEAD moded) WITTH (concentited hallow onesed halaet)) and	IBM_TDB USPAT;	2004/02
13	79	((die NEAR pad\$4) WITH (concavit\$3 hollow open\$3 hole\$1)) and ((lead NEAR frame) WITH (tie NEAR bar\$1))	US-PGPUB;	2007/02
		((lead 1124 IIC Hallie) WITTI (de 112/11C oatwi))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	<u> </u>

	Hits	Search Text	DB	Time st
1	20324	flip NEAR chip	USPAT;	2004/02
			US-PGPUB;	
			EPO; JPO;	
]			DERWENT;	
		a	IBM_TDB	2004/00
2	20325	flip NEAR chip\$1	USPAT;	2004/02
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT; IBM_TDB	
3	120	(flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow	USPAT;	2004/02
]	120	open\$3 hole\$1))	US-PGPUB;	2004/02
		openus noteur))	ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
4	19	(flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow	USPAT;	2004/02
'	17	open\$3 hole\$1) WITH bump\$1)	US-PGPUB;	
1			ЕРО; ЛРО;	
		·	DERWENT;	
			IBM_TDB	
5	28	("3648002"   "3832632"   "3971610"   "4288841"   "4329642"	USPAT	2004/02
		"4340860"   "4437718"   "4554505"   "4739257"   "4899107"		
		"4956605"   "5006792"   "5006796"   "5014161"   "5061192"		
		"5123850"   "5173451"   "5207585"   "5248262"   "5302891"		
		"5329423"   "5358417"   "5453701"   "5475315"   "5489854"		
-		"5493237"   "5633596"   "5656945").PN.	7.70D 4.00	2004/00
6	93	((flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow	USPAT;	2004/02
		open\$3 hole\$1))) and bump\$1	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
7	74	(((flip NEAR chip\$1) and ((die NEAR pad\$4) WITH (concavit\$3 hollow	USPAT;	2004/02
'	/4	open\$3 hole\$1))) and bump\$1) and (bond\$3 NEAR pad\$1)	US-PGPUB;	2004/02
		openso notest ))) and ounipst) and (ooldso trizate padst)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
8	53	(flip NEAR chip\$1) and ((lead NEAR frame) WITH (tie NEAR bar\$1))	USPAT;	2004/02
			US-PGPUB;	]
1 1			EPO; JPO;	
			DERWENT;	
1		•	IBM_TDB	
9	7	("5091341"   "5147821"   "5200809"   "5202288"   "5387554"	USPAT	2004/02
		"5442234"   "5570272").PN.	1100.45	2001/01
10	6	("3729573"   "4377548"   "4470786"   "4626185"   "4823234"	USPAT	2004/02
	3.4	"4954307").PN.	IICDAT.	2004/02
11	34	((die NEAR pad\$4) WITH (concavit\$3 hollow open\$3 hole\$1) WITH	USPAT; US-PGPUB;	2004/02
		bump\$1)	EPO; JPO;	!
			DERWENT;	
			IBM_TDB	
12	994	(die NEAR pad\$4) WITH (concavit\$3 hollow open\$3 hole\$1)	USPAT;	2004/02
	777	(are reserved to the reserved	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
13	79	((die NEAR pad\$4) WITH (concavit\$3 hollow open\$3 hole\$1)) and	USPĀT;	2004/02
		((lead NEAR frame) WITH (tie NEAR bar\$1))	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	L

14	18	thermal\$2 NEAR conduct\$3 NEAR bump\$1	USPAT;	2004/02
- '		1	US-PGPUB;	
		*	ЕРО; ЈРО;	
			DERWENT;	
Ì			IBM_TDB	
15	2	("6331451").PN.	USPAT;	2004/02
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
,,		CHO 1//1 (APPAD) 1 AVAPPELL 1 : ANA DAT	IBM_TDB	2004/02
16	0	("2and((heatNEARspreader)WITHchip)").PN.	USPAT; US-PGPUB;	2004/02
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
17	303	(flip NEAR chip\$1) and ((heat NEAR spreader) WITH chip)	USPAT;	2004/02
1′	303	(mp 1423 ht ompor) and (meat 1423 ht opicades) with omp	US-PGPUB;	
			ЕРО; ЛРО;	
}			DERWENT;	
			IBM TDB	
18	0	((flip NEAR chip\$1) and ((heat NEAR spreader) WITH chip)) and ((die	USPAT;	2004/02
		NEAR pad\$4) WITH (concavit\$3 hollow open\$3 hole\$1))	US-PGPUB;	
	]		ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
19	0	((flip NEAR chip\$1) and ((heat NEAR spreader) WITH chip)) and	USPAT;	2004/02
		((lead NEAR frame) WITH (tie NEAR bar\$1))	US-PGPUB;	
			ЕРО; ЈРО;	
	1		DERWENT;	
		COLUMN TO A COLUMN	IBM_TDB	2004/01
20	186	((flip NEAR chip\$1) and ((heat NEAR spreader) WITH chip)) and	USPAT;	2004/02
İ		bump\$1	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
21	77	(((flip NEAR chip\$1) and ((heat NEAR spreader) WITH chip)) and	USPAT;	2004/02
21	· · ·	bump\$1) and (bond\$3 NEAR pad\$1)	US-PGPUB;	
	†	oumput) and (outdo 1122 at page)	ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
22	0	(flip NEAR chip\$1) and (heat NEAR transmission NEAR (layer film))	USPAT;	2004/02
			US-PGPUB;	
			ЕРО; ЛРО;	
		·	DERWENT;	
			IBM_TDB	2004/01
23	1	chip WITH (heat NEAR transmission NEAR (layer film))	USPAT;	2004/02
	1		US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
24	7	chip and (heat NEAR transmission NEAR (layer film))	USPAT;	2004/02
24	'	omp and (near rations dansinission rations (layer min))	US-PGPUB;	200-1102
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
25	0	(active NEAR surface NEAR chip) WITH (electrically NEAR	USPAT;	2004/02
		connect\$3) WITH (tie NEAR bar\$1)	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	l

27	7	(chip\$1 WITH (electrically NEAR connect\$3) WITH (tie NEAR bar\$1))	USPAT;	2004/02
	,	and active	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
28	3	(chip\$1 WITH (electrically NEAR connect\$3) WITH (tie NEAR bar\$1))	USPAT;	2004/02
		and (flip NEAR chip\$1)	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
29	3	(chip\$1 WITH (electrically NEAR connect\$3) WITH (tie NEAR bar\$1))	USPAT;	2004/02
1		and ((flip NEAR chip\$1) and ((lead NEAR frame) WITH (tie NEAR	US-PGPUB;	
		bar\$1)))	ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
30	6	("4534105"   "5198886"   "5331203"   "5583370"   "5684330"	USPAT	2004/02
	1	"5821615").PN.		
26	47	chip\$1 WITH (electrically NEAR connect\$3) WITH (tie NEAR bar\$1)	USPAT;	2004/02
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	